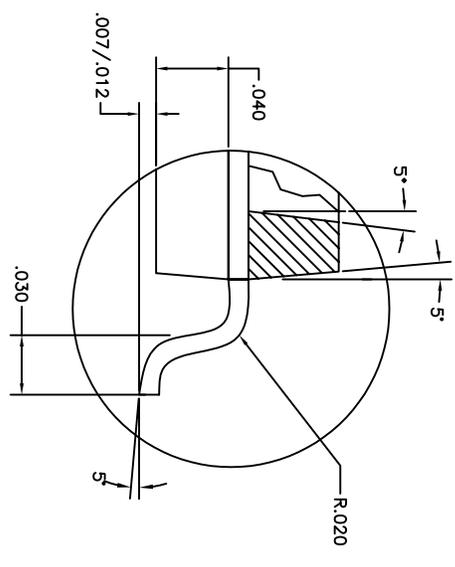
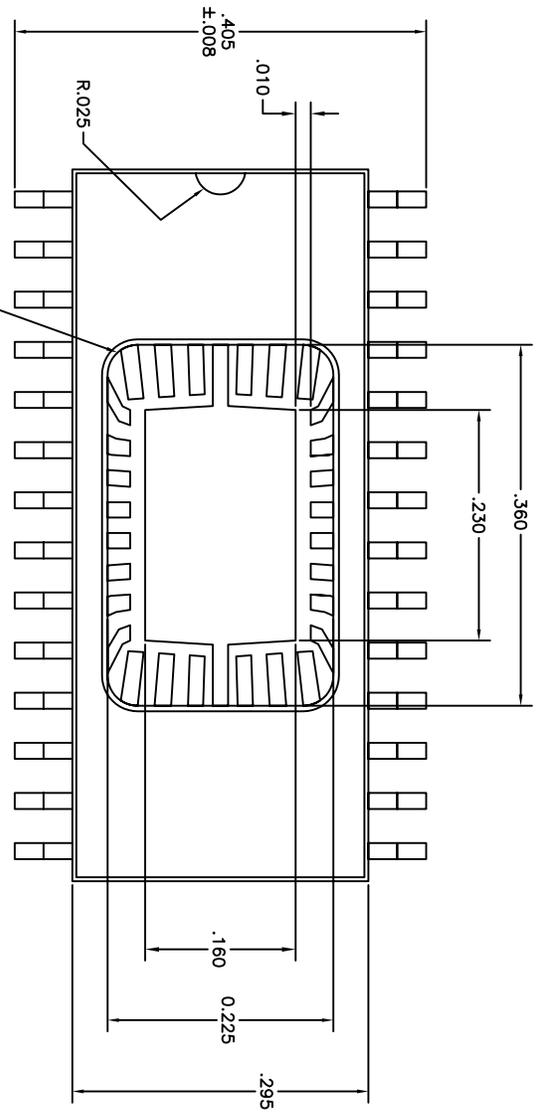


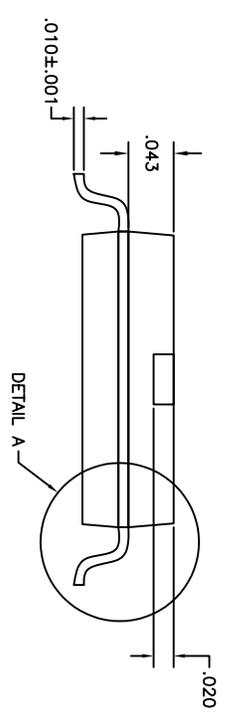
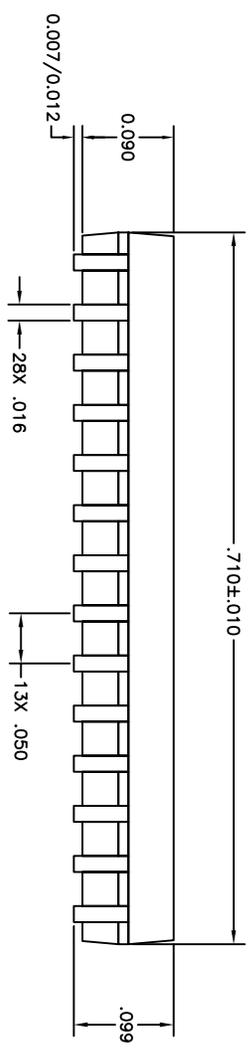
2

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REVISIONS		APPROVED
ECON NO.	DATE	DESCRIPTION
10793	11/02/06	PRODUCTION RELEASE
		D.BENANDIO



DETAIL A
SCALE: 2/1



DETAIL A

NOTES:

- BODY: PLASTIC, SEMICONDUCTOR GRADE.
- LEADFRAME: COPPER, FH 194.
- LEAD FINISH: FULL AU PLATE.
- DIE PAD: .230" x .160".



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
XXX ± 0.01 X.XXXX ± ---
XXXX ± 0.005 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN C. CRUZ	DATE 11/01/06
APP P. FLASKERUD	DATE 11/01/06
CUSTOMER ---	

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SIZE A	PART NO. SOIC300-28-0P-01	REV 4
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